

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT3936422

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
KOICHI SHIMAZAKI	06/21/2016
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SII SEMICONDUCTOR CORPORATION
<b>Street Address:</b>	8, NAKASE 1-CHOME, MIHAMA-KU
<b>City:</b>	CHIBA-SHI, CHIBA
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	261-8507
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15193386
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(212)809-3704
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	212-809-3700
<b>Email:</b>	adamswilks@aol.com
<b>Correspondent Name:</b>	ADAMS & WILKS
<b>Address Line 1:</b>	17 BATTERY PLACE
<b>Address Line 2:</b>	SUITE 1343
<b>Address Line 4:</b>	NEW YORK, NEW YORK 10004
<b>ATTORNEY DOCKET NUMBER:</b>	S005-7411
<b>NAME OF SUBMITTER:</b>	BRUCE L. ADAMS
<b>SIGNATURE:</b>	/bruce l. adams/
<b>DATE SIGNED:</b>	06/27/2016
<b>Total Attachments: 2</b>	
source=15193386ASG_20160627134042#page1.tif	
source=15193386ASG_20160627134042#page2.tif	

ASSIGNMENT

WHEREAS, I, Koichi SHIMAZAKI, residing at c/o SII Semiconductor Corporation, 8, Nakase 1-chome, Mihama-ku, Chiba-shi, Chiba, 261-8507, Japan, have invented new and useful improvements in SEMICONDUCTOR DEVICE, for which I have prepared an application for Letters Patent of the United States of America;

AND WHEREAS, SII Semiconductor Corporation, a Japanese corporation located and doing business at 8, Nakase 1-chome, Mihama-ku, Chiba-shi, Chiba, 261-8507, Japan, is desirous of acquiring an interest therein and in the Letters Patent to be obtained therefor;

NOW, THEREFORE, be it known by all whom it may concern, that for and in consideration of Ten Dollars (\$10.00) and other good and valuable consideration to me in hand paid, the receipt of which is hereby acknowledged, I have assigned, sold and transferred and by these presents do hereby assign, sell and transfer unto the said SII Semiconductor Corporation for the territory of the United States of America, my entire right, title and interest in and to the said invention, and in and to the said application, prepared and executed by me on June 17, 2016, filed June 27, 2016, Appln. No. 15/193,386, preparatory to obtaining Letters Patent thereon and in and to any and all divisions, reissues and continuations thereof, and in and to any Letters Patent that may be granted thereon; said invention, application and Letters Patent to be held and enjoyed by the said

SII Semiconductor Corporation, its legal representatives and assigns, as fully and entirely as the same would have been held by me had this assignment, sale and transfer not been made.

AND, I hereby covenant and agree that I will at any time upon the request and at the expense of said assignee execute and deliver any and all papers and do all lawful acts that may be necessary or desirable to perfect the title to said invention and to obtain Letters Patent therefor, and I hereby authorize and request the Honorable Commissioner of Patents and Trademarks to issue the said Letters Patent to the said SII Semiconductor Corporation in accordance with this assignment.

Executed this 21st day of June, 2016.

Witness:

Koichi Shimazaki (L.S.)  
Koichi SHIMAZAKI